



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Application Serial No. 09/784,234
Filing Date February 14, 2001
Inventor Nagano et al.
Assignee Honeywell International Inc. #19
Group Art Unit 1742
Examiner Ip, Sikyin
Attorney's Docket No. 30-5000-(4015)-DIV1
Title: Conductive Integrated Circuit Metal Alloy Interconnections, Electroplating Anodes,
Metal Alloys For Use As A Conductive Interconnection In An Integrated Circuit, and
Physical Vapor Deposition Targets

SUPPLEMENTAL INFORMATION DISCLOSURE STATEMENT

RECEIVED
MAR 14 2003
TC 1700

To: Assistant Commissioner for Patents
Washington, D.C. 20231

From: Jennifer J. Taylor, Ph.D. (Tel. 509-624-4276; Fax 509-838-3424)
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601 W. First Avenue, Suite 1300
Spokane, WA 99201-3828

Dear Sir:

The Examiner's attention is directed to the references which are listed on
the attached Form PTO-1449 and copies of which are attached.

Citation of these references is respectfully requested.

Respectfully submitted,

Dated: March 10, 2003 By: Jennifer J. Taylor
Jennifer J. Taylor, Ph.D.
Reg. No. 48,711